

Amendments to the Specification:

Please add the following new paragraph before the first line:

--This application is a divisional of U.S. Patent Application Serial No. 09/855,244, entitled "MULTI-CHIP SEMICONDUCTOR PACKAGE WITH INTEGRAL SHIELD AND ANTENNA", filed on May 14, 2001.--

Please replace the paragraph beginning at page 11, line 18, with the following rewritten paragraph:

--FIG. 3 is a bottom plan view of antenna shield assembly 150 of transceiver package 100 of FIGS. 1 and 2 in accordance with one embodiment of the present invention. Referring now to FIGS. 1, 2 and 3 together, shield 152 is formed of an electrically conductive material. Illustratively, shield 152 is formed of a stamped, formed or deposited metal such as stainless-steel, copper or tin alloy. In this embodiment, shield 152 is in the shape of a hollow rectangular box having its bottom missing. Stated another way, shield 152 is a rectangular lid.--

Please replace the paragraph beginning at page 19, line 31, with the following rewritten paragraph:

--Second, shield 152 is a ground plane for antenna 156. Advantageously, antenna 156 is fabricated as part of transceiver package 100. This is in stark contrast to the prior art where the antenna, which was a structure separate from the integrated circuit package, was attached separately to the printed circuit mother board. By incorporating antenna 156 into transceiver package 100, an electronic device, e.g., cellular telephone, employing transceiver package 100 in accordance with the present invention is fabricated to be smaller, lighter and less expensive than an electronic device of the prior art.--